imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

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5.0mm x 6.0mm SURFACE MOUNT LED LAMP

ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES

Features

- Chips can be controlled separately.
- Suitable for all SMT assembly and solder process.
- Available on tape and reel.
- Package: 500pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Part Number: AAAF5060QBFSURZGS

Blue Hyper Red Green

Description

The Blue source color devices are made with InGaN Light Emitting Diode.

The Hyper Red source color devices are made with Al-

GaInP on GaAs substrate Light Emitting Diode.

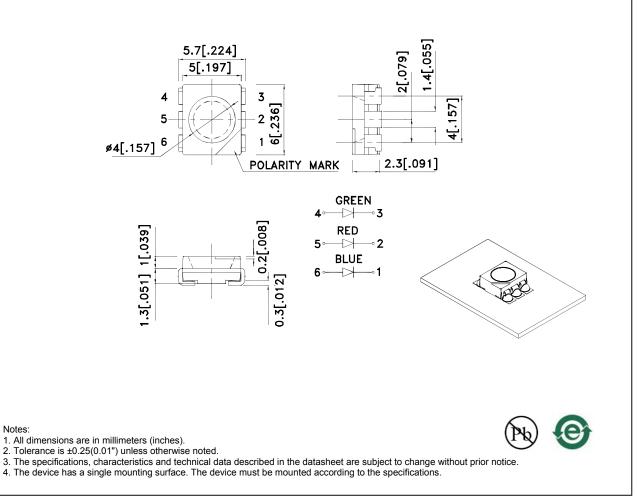
The Green source color devices are made with InGaN on Sapphire Light Emitting Diode.

Static electricity and surge damage the LEDS.

It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically grounded.



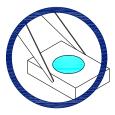


SPEC NO: DSAL0957 APPROVED: WYNEC REV NO: V.1 CHECKED: Allen Liu DATE: OCT/06/2010 DRAWN: F.F.Zhou PAGE: 1 OF 8 ERP: 1201007061

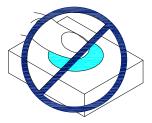
Handling Precautions

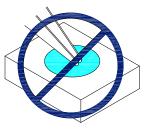
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force. As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.

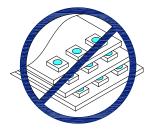


2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.





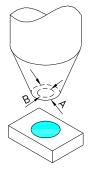
3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



4. The outer diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks. The inner diameter of the nozzle should be as large as possible.

5. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.

6. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



Selection Guide lv (mcd) [2] Viewing @ 30mA *50mA Angle [1] Part No. Dice Lens Type 201/2 Min. Тур. Blue (InGaN) 280 400 AAAF5060QBFSURZGS Hyper Red (AlGaInP) Water Clear *500 *800 100° Green (InGaN) 500 1000

Notes:

θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
*Luminous intensity with asterisk is measured at 50mA; Luminous intensity/ luminous Flux: +/-15%.

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Blue Hyper Red Green	461 650 515		nm	I⊧=20mA
λD [1]	Dominant Wavelength	Blue Hyper Red Green	465 630 525		nm	I⊧=20mA
Δλ1/2	Spectral Line Half-width	Blue Hyper Red Green	25 27 30		nm	I⊧=20mA
С	Capacitance	Blue Hyper Red Green	100 45 45		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Blue Hyper Red Green	3.3 1.9 3.3	4 2.5 4.1	V	I⊧=20mA
lr	Reverse Current	Blue Hyper Red Green		50 10 50	uA	Vr=5V

Electrical / Optical Characteristics at TA=25°C

Notes:

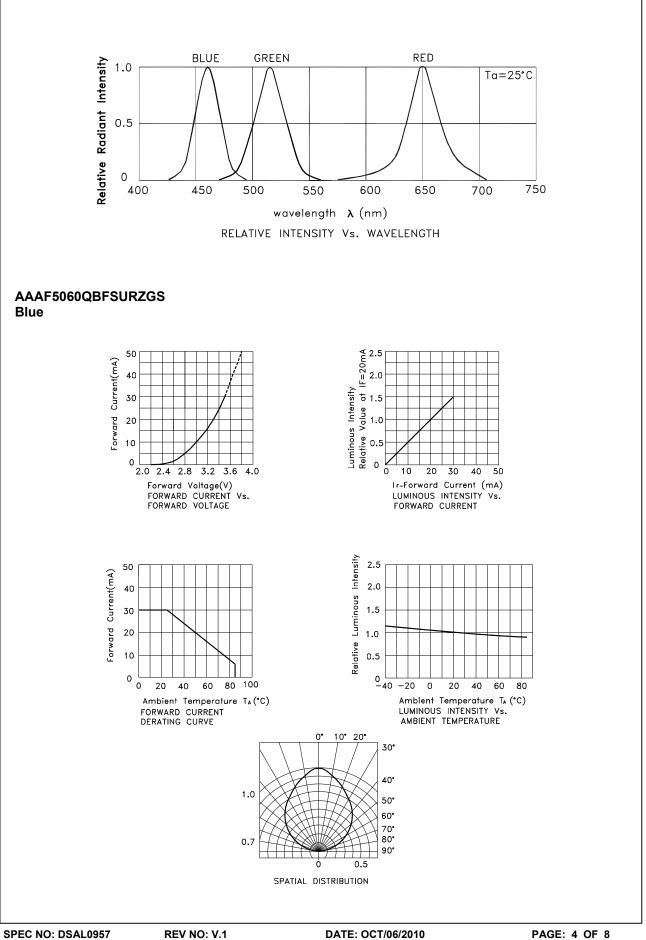
1.Wavelength: +/-1nm.

2. Forward Voltage: +/-0.1V.

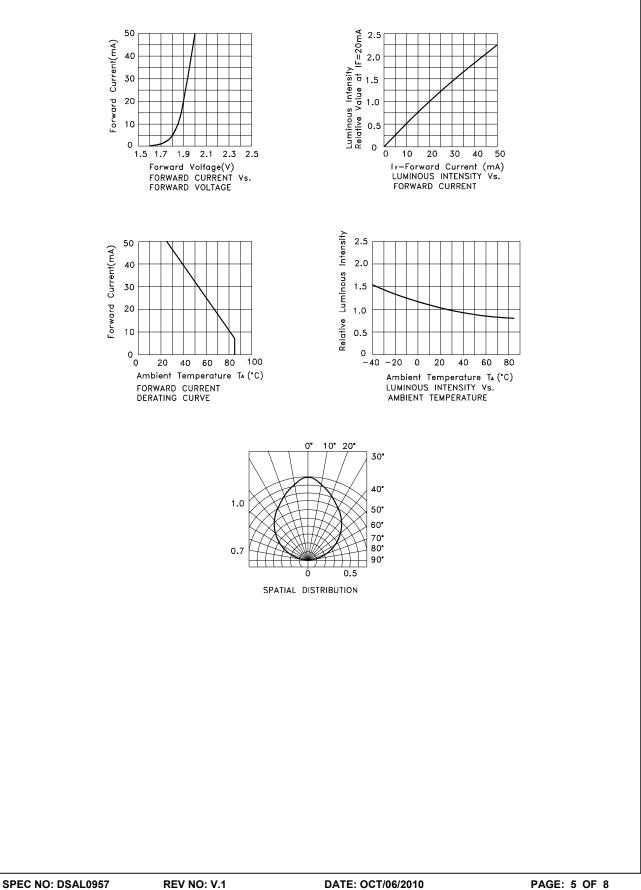
Absolute Maximum Ratings at TA=25°C

Parameter	Blue	Hyper Red	Green	Units			
Power dissipation[2]	350						
DC Forward Current	30	50	30	mA			
Peak Forward Current [1]	150	185	150	mA			
Reverse Voltage		V					
Operating Temperature	-40°C To +85°C						
Storage Temperature	-40°C To +85°C						

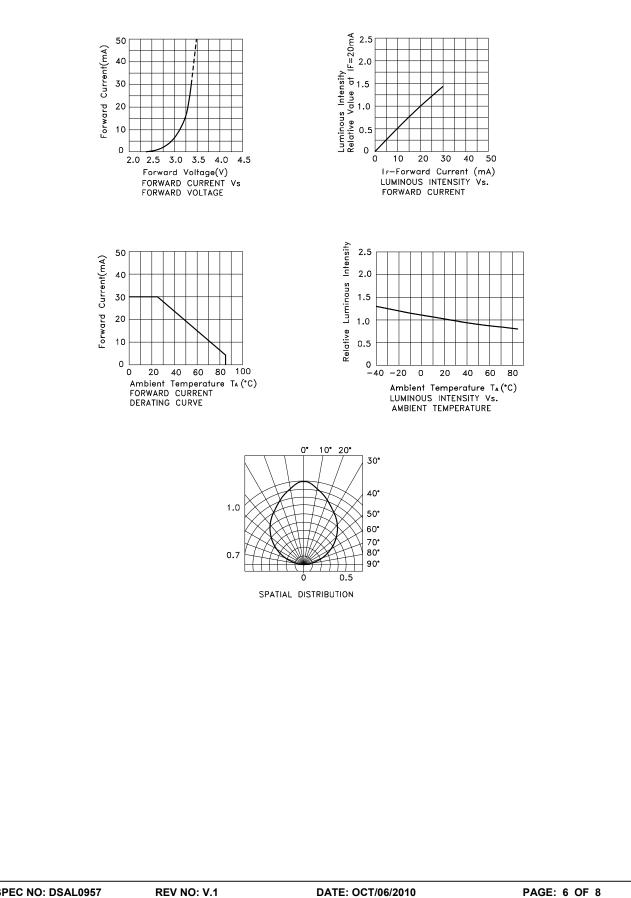
Notes: 1. 1/10 Duty Cycle, 0.1ms Pulse Width. 2. Within 350mW at all chips are lightened.



Hyper Red



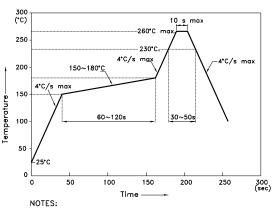
Green



AAAF5060QBFSURZGS

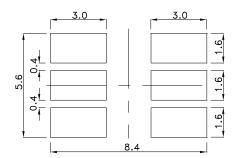
Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

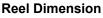
Reflow Soldering Profile For Lead-free SMT Process.

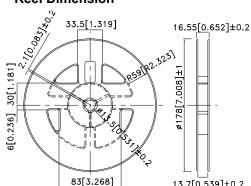


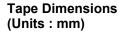
NOTES: 1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature. 3.Number of reflow process shall be 2 times or less.

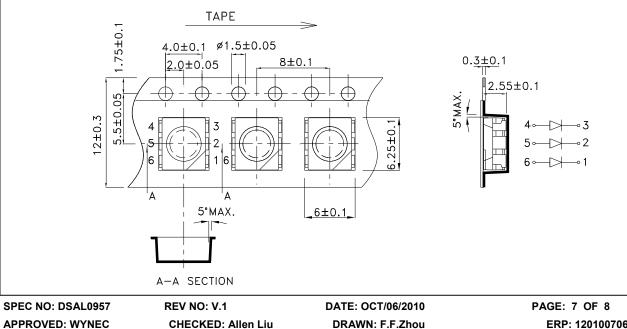












DRAWN: F.F.Zhou

13.7[0.539]±0.2

